

HI1172

6-Bit, 20 MSPS, Video A/D Converter (CMOS)

August 1997

Features • Resolution 6-Bit • Maximum Sampling Frequency 20 MSPS • Low Power Consumption at 20 MSPS (Typ) (Reference Current Excluded) 40mW • Built-In Sample and Hold Circuit • Three-State TTL Compatible Output • Power Supply 5V Single • Low Input Capacitance 4pF • Reference Impedance 250Ω (Typ)

Description

HI1172 is a 6-bit, CMOS A/D converter for video use. The adoption of a 2-step parallel conversion achieves speeds of 20 MSPS minimum, 35 MSPS typical.

Ordering Information

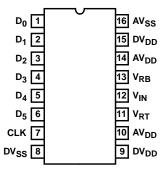
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.	
HI1172JCP	-20 to 75	16 Ld PDIP	E16.3A-S	
HI1172JCB	-20 to 75	16 Ld SOIC	M16.2-S	

Applications

- · Video Digitizing
- Wireless Communications

Pinout

HI1172 (PDIP, SOIC) TOP VIEW



HI1172 Functional Block Diagram REFERENCE VOLTAGE (16) AV_{SS} D0 (15) DV_{DD} D1 LOWER LOWER ENCODER (3-BIT) LOWER COMPARATORS WITH S/H (3-BIT) DATA LATCHES (14) AV_{DD} D2 (13) V_{RB} D3 LOWER ENCODER LOWER COMPARATORS WITH S/H (3-BIT) (12) V_{IN} D4 (3-BIT) UPPER DATA LATCHES (11) v_{RT} D5 (10) AV_{DD} UPPER COMPARATORS WITH S/H (3-BIT) **UPPER** CLK (7 **ENCODER** (9) DV_{DD} D_{VSS} (8) (3-BIT) **CLOCK GENERATOR Typical Application Circuit** \sim \odot $\boldsymbol{v}_{\text{IN}}$ (LSB) D0 D1 D2 +5V v_{RB} D3 V_{IN} D4 (MSB) D5 V_{RT} - +5V C2

· V_{RT}

 V_{RB}

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Pin Descriptions

NUMBER	SYMBOL	EQUIVALENT CIRCUIT	DO (LSB) to D5 (MSB) Output.			
1 to 6	D0 to D5					
7	CLK	7 — W DV _{SS}	Clock Input.			
8	DV _{SS}		Digital GND.			
9, 15	DV _{DD}		Digital +5V.			
10, 14	AV _{DD}		Analog +5V.			
11	V _{RT}	φ AV _{DD}	Reference Voltage (Top).			
13	V_{RB}	11 AV _{SS}	Reference Voltage (Bottom).			
12	V _{IN}	AV _{DD} (12) AV _{SS}	Analog Input.			
16	AV _{SS}		Analog GND.			

Absolute Maximum Ratings $T_A = 25^{\circ}C$

Operating Conditions

Supply Voltage Range, AV _{DD} , AV _{SS} 4.75V to 5.25V Reference Voltage, DV _{DD} , DV _{SS}
V _{RT}
V _{RB}
V _{RT} - V _{RB}
Analog Input Voltage (V _{IN})V _{RB} to V _{R1}
Clock Pulse Width
t _{PW1}
t _{PW0}
Temperature Range20°C to 75°C

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)
SOIC Package	120
PDIP Package	94
Maximum Junction Temperature (Plastic Package)	150 ^o C
Maximum Storage Temperature Range65	5°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications $V_{DD} = +5V$, $V_{RB} = 1V$, $V_{RT} = 2V$, $T_A = 25^{\circ}C$

PARAMETER	SYMBOL	TEST	MIN	TYP	MAX	UNITS	
Conversion Speed, f _C	f _C	$V_{IN} = 1V \text{ to } 2V$ $f_{IN} = 1kHz \text{ Ran}$	0.5	-	20	MSPS	
Integral Non-Linearity	EL	$f_C = 20 \text{ MSPS}$ $V_{IN} = 1V \text{ to } 2V$	-	±0.3	±0.5	LSB	
Differential Non-Linearity	E _D		f _C = 20 MSPS V _{IN} = 1V to 2V			±0.5	LSB
Supply Current	I _{DD}	f _C = 20 MSPS NTSC Ramp V	f _C = 20 MSPS NTSC Ramp Wave Input			12	mA
Reference Pin Current	I _{REF}			3	4	5.7	mA
Analog Input (-1dB)	BW			-	18	-	MHz
Analog Input Capacitance	C _{IN}	V _{IN} = 1.5V + 0.07V _{RMS}		-	4	-	pF
Reference Resistance (V _{RT} to V _{RB})	R _{REF}			175	250	325	Ω
Offset Voltage	E _{OT}			0	-20	-40	mV
	E _{OB}	1		15	35	55	mV
Digital Input Voltage	V _{IH}			4.0	-	-	V
	V _{IL}	1		-	-	1.0	V
Digital Input Current	I _{IH}	V _{DD} = Max	$V_{IH} = V_{DD}$	-	-	5	μΑ
	I _{IL}	1	V _{IL} = 0V	-	-	5	μΑ
Digital Output Current	I _{OH}	V _{DD} = Min	$V_{OH} = V_{DD} = 0.5V$	-1.1	-	-	mA
	l _{OL}	1	V _{OL} = 0.4V	3.7	-	-	mA
Output Data Delay	T _{DL}	With TTL 1 Gate and 10pF Load		-	18	30	ns
Differential Gain Error	DG	NTSC 40 IRE Mod		-	1.0	-	%
Differential Phase Error	DP	Ramp, f _C = 14.3 MSPS		-	1.0	-	deg
Aperture Jitter	t _{AJ}			-	40	-	ps
Sampling Delay	t _{SD}			-	4	-	ns

Test Circuits

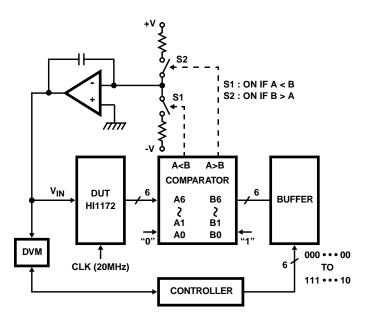


FIGURE 1. INTEGRAL NON-LINEARITY ERROR, DIFFERENTIAL NON-LINEARITY, OFFSET VOLTAGE

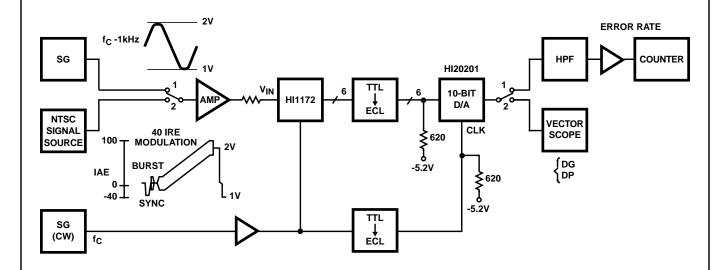


FIGURE 2. MAXIMUM OPERATIONAL SPEED, DIFFERENTIAL GAIN ERROR, DIFFERENTIAL PHASE ERROR

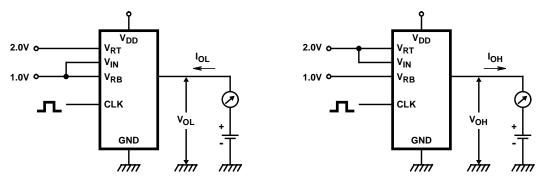
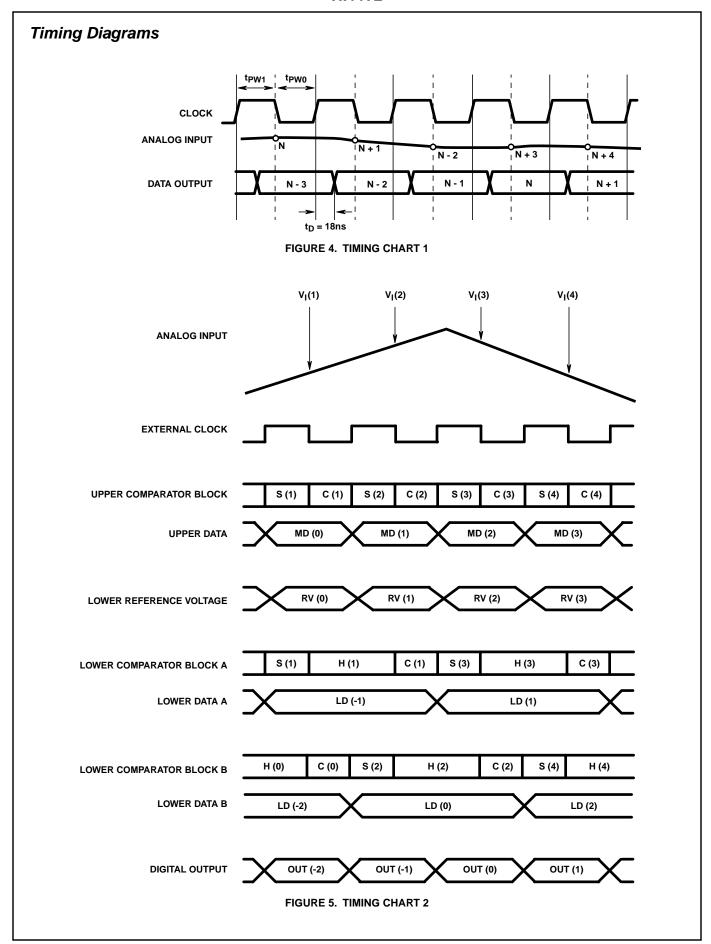


FIGURE 3. DIGITAL OUTPUT CURRENT TEST CIRCUIT



Digital Output

Compatibility between analog input voltage and the digital output code is indicated in the chart below.

INPUT SIGNAL		DIGITAL OUTPUT CODE						
VOLTAGE	STEP	MSB					LSB	
V _{RT}	0	1	1	1	1	1	1	
•	•			•	•			
•	•				•			
•	•		•					
•	31	1	0	0	0	0	1	
•	32	0	1	1	1	1	1	
•	•	•						
	•				•			
	•				•			
V _{RB}	63	0	0	0	0	0	0	

Operation (See Block Diagram and Waveform)

The HI1172 is a 2-step parallel system A/D converter featuring a 3-bit upper comparators group and 2 lower comparators groups of 3-bit each. The reference voltage that is equal to the voltage between $V_{RT}V_{RB}/8$ is constantly applied to the upper 3-bit comparator block. Voltage that corresponded to the upper data is fed through the reference supply to the lower data.

This IC uses an offset cancel type comparator and operates synchronously with an external clock. It features the following operating modes which are respectively indicated on the timing chart with S, H, C symbols, i.e., input sampling (auto zero) mode, input hold mode and comparison mode.

The operation of respective parts is as indicated in the chart. Input voltage Vi (1) is sampled with the falling edge of the first clock by means of the upper comparator block and the lower comparator A block.

The upper comparators block finalizes comparison data MD (1) with the rising edge of the first clock. simultaneously the reference supply generates the lower reference voltage RV (1) that corresponded to the upper results. The lower comparator block finalizes comparison data LD (1) with the rising edge of the second clock. MD (1) and LD (1) are combined and output as Out (1) with the rising edge of the 3rd clock. Accordingly there is a 2.5 clock delay from the analog input sampling point to the digital data output.

Notes On Operation

- V_{DD}, V_{SS} To reduce noise effects, separate the analog and digital systems close to the device. For both the digital and analog V_{DD} pins, use a ceramic capacitor of about 0.1μF set as close as possible to the pin to bypass to the respective GNDs.
- Analog Input Compared with a flash type A/D converter, the input capacitance of the analog input is rather small. However it is necessary to drive with an amplifier featuring sufficient bandwidth and drive capability. When driving with an amplifier of low output impedance, parasitic oscillation may occur. That may be prevented by inserting a resistance of about 100Ω in series between the amplifier output and A/D input.
- Clock Input The clock line wiring should be as short as possible. Also, to avoid any interference with other signals, separate it from the other circuits.
- Reference Input Voltage between V_{RT} to V_{RB} is compatible with the dynamic range of the analog input. By bypassing V_{RT} and V_{RB} pins to GND with a capacitor of about $0.1\mu F$, stable characteristics are obtained.
- Timing Analog input is sampled with the falling edge of CLK and output as digital data with a delay of 2.5 clocks and with the following rising edge. The delay from the clock rising edge to the data output is about 18ns.
- About Latch Up It is necessary that AV_{DD} and DV_{DD} pins to be the common source of power supply. This is to avoid latch up due to the voltage difference between AV_{DD} and DV_{DD} pins when power is ON.

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